

# UP SuperServer SYS-111C-NR

1U UP CloudDC with 10 hot-swap 2.5" NVMe/SAS/SATA bays and 2 PCIe 5.0 slots + 2 PCIe 5.0 AIOM slots



More details here

## Key Applications

Virtualization, HPC, CDN, Edge Nodes, Cloud Computing, Data Center  
Optimized, Storage Headnode,

## Key Features

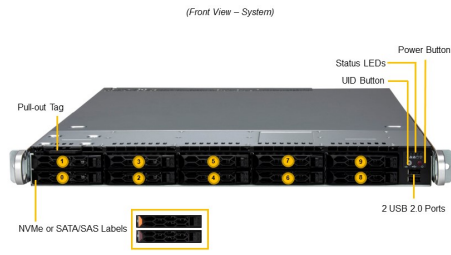
- Single Socket E (LGA-4677) 4th/5th Gen Intel® Xeon® Scalable processors. Up to 350W TDP;
- Intel® C741 Chipset;
- 16 DIMMs; Supports 3DS DDR5 RDIMM. Up to 5600 MHz;
- Dual AIOM (OCP 3.0) for networking (NCSI available), 1 dedicated IPMI LAN;
- 10x front hot-swap 2.5" SATA3 drive bays (Optional all 10 hybrid Gen5 NVMe), SAS3 with additional SAS controller card;
- Redundant Now Titanium 860W Power Supplies;



<b>Form Factor</b>	<p>1U Rackmount</p> <p>Enclosure: 437 x 43 x 597mm (17.2" x 1.7" x 23.5")</p> <p>Package: 605 x 197 x 822mm (23.8" x 7.8" x 32.4")</p>
<b>Processor</b>	<p>Single Socket E (LGA-4677)</p> <p>5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors</p> <p>Up to 64C/128T; Up to 320MB Cache</p>
<b>GPU</b>	<p>Max GPU Count: Up to 2 single-width GPUs</p> <p>Supported GPU: NVIDIA PCIe: T1000, L4, A2</p> <p>CPU-GPU Interconnect: PCIe 5.0 x16 CPU-to-GPU Interconnect</p>
<b>System Memory</b>	<p>Slot Count: 16 DIMM slots/8 Channels</p> <p>Max Memory (1DPC): Up to 2TB 5600MT/s ECC DDR5 RDIMM</p> <p>Max Memory (2DPC): Up to 4TB 4400MT/s ECC DDR5 RDIMM</p>
<b>Drive Bays Configuration</b>	<p>Default: Total 10 bays</p> <ul style="list-style-type: none"> <li>• 10 front hot-swap 2.5" SAS*/SATA drive bays</li> </ul> <p>Option A: Total 10 bays</p> <ul style="list-style-type: none"> <li>• 6 front hot-swap 2.5" SAS*/SATA drive bays</li> <li>• 4 front hot-swap 2.5" PCIe 5.0 x4 NVMe*/SAS*/SATA drive bays</li> </ul> <p>Option B: Total 10 bays</p> <ul style="list-style-type: none"> <li>• 10 front hot-swap 2.5" PCIe 5.0 x4 NVMe*/SAS*/SATA drive bays</li> </ul> <p>(*NVMe/SAS support may require additional storage controller and/or cables, please see the optional parts list for details)</p> <p>M.2: 2 M.2 PCIe 3.0 x2 NVMe slots (M-key 2280/22110)</p>
<b>Expansion Slots</b>	<p>Default</p> <ul style="list-style-type: none"> <li>• 2 PCIe 5.0 x16 FHHL slots</li> <li>• 2 PCIe 5.0 x16 AIOM slots (OCP 3.0 compatible)</li> </ul> <p>Option A</p> <ul style="list-style-type: none"> <li>• 2 PCIe 5.0 x16 FHHL slots</li> <li>• 1 PCIe 5.0 x8 AIOM slot (OCP 3.0 compatible)</li> <li>• 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)</li> </ul> <p>Option B</p> <ul style="list-style-type: none"> <li>• 2 PCIe 5.0 x16 FHHL slots</li> <li>• 1 PCIe 5.0 x8 AIOM slot (OCP 3.0 compatible)</li> </ul>
<b>On-Board Devices</b>	<p>SATA: SATA (6Gbps) ; RAID 0/1/5/10 support</p> <p>NVMe: NVMe; RAID 0/1/5/10 support(Intel® VROC RAID key required)</p> <p>Chipset: Intel® C741</p> <p>Network Connectivity: Via AIOM</p>
<b>Input / Output</b>	<p>LAN: 1 RJ45 1 GbE Dedicated BMC LAN port</p> <p>USB: 2 USB 3.2 Gen1 Type-A ports(rear)</p> <p>2 USB 2.0 Type-A ports(front)</p>

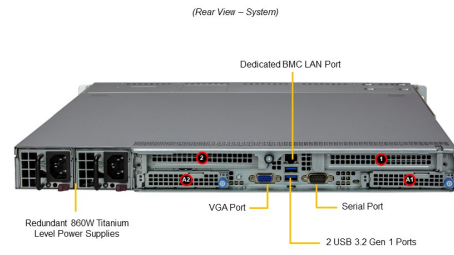
Video: 1 VGA port  
Serial: 1 COM port(Rear)  
TPM: 1 TPM header

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Drive Bay	Description
1 - 2	2.5" Hot-swap PCIe 5.0 NVMe/SAS3/SATA3 Drive Bays

\* NVMe or SAS3 support requires additional parts from the optional parts list



Slot Description	
1 - 2	PCIe 5.0 x16 FHFL
3 - 4	PCIe 5.0 x16 AOM (OCP 3.0)

\* Default Configuration. Exact slot quantity depends on the system board.

System Cooling	Fans: 6 middle cooling PWM 40x40x56mm Fan(s) Air Shroud: 1 Air Shroud
Power Supply	2x 860W Redundant (1 + 1) Titanium Level (96%) power supplies
System BIOS	BIOS Type: AMI 32MB SPI Flash EEPROM
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Supermicro Update Manager (SUM); Supermicro SuperDoctor® 5 (SD5); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory 8 Phase-switching voltage regulator FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors
Dimensions and Weight	Weight: Gross Weight: 40 lbs (18.1 kg) Net Weight: 25 lbs (11.3 kg) Available Color: Black front & silver body
Operating Environment	Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -30°C to 60°C (-22°F to 140°F) Operating Relative Humidity: 8% to 80% (non-condensing) Non-operating Relative Humidity: 8% to 90% (non-condensing)
Motherboard	<a href="#"><b>Super X13SEDW-F</b></a>
Chassis	<b>CSE-LB16TS-R0AWNP3</b>